

1 2 3 4 5 6 7 8

F

E

D

C

B

A

F

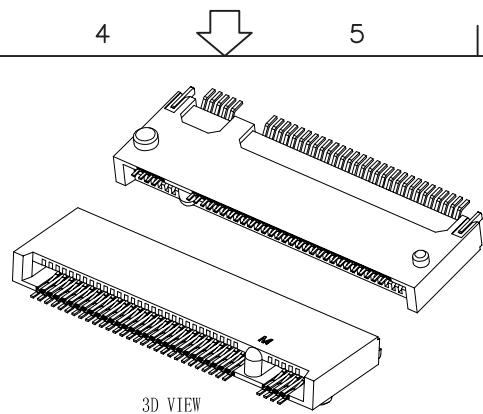
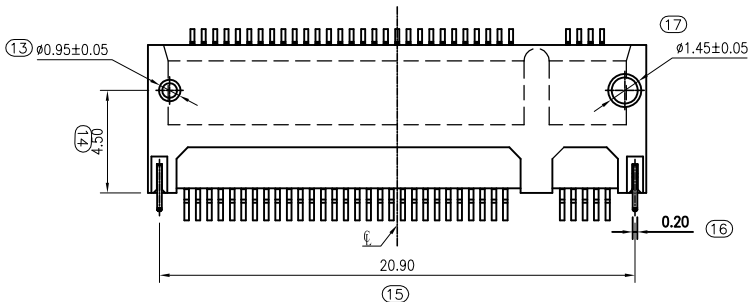
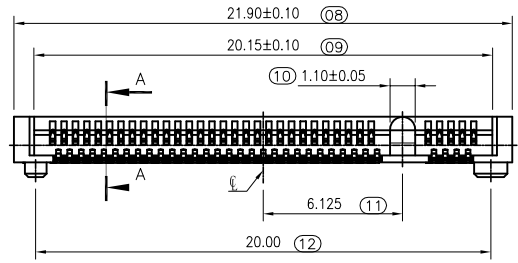
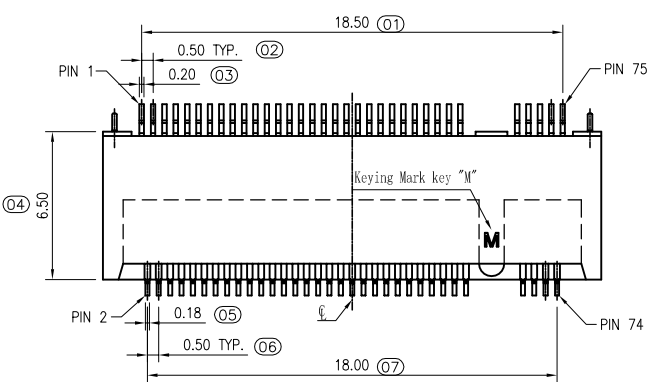
E

D

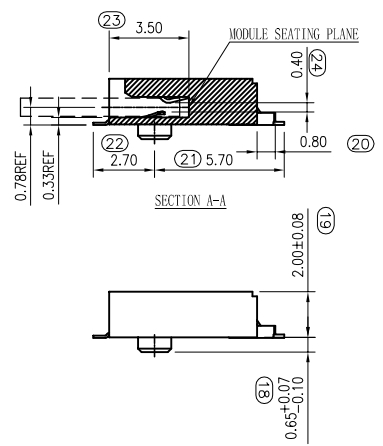
C

B

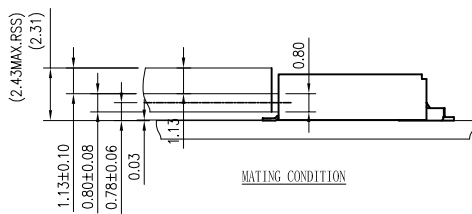
A



3D VIEW



SECTION A-A



MATING CONDITION

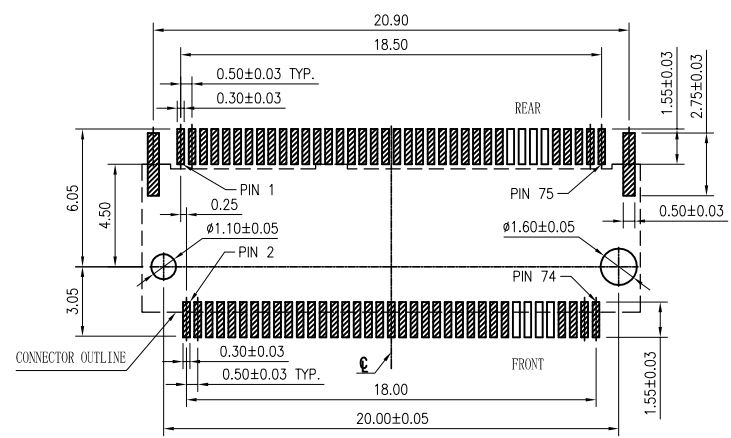
NOTE:
PRODUCTS MUST CONFORM TO JS SPEC JS-GC03143-A1.

1.MATERIAL:

HOUSING: LCP; UL94V-0; COLOR:BLACK
UPPER CONTACT: C5210. T=0.15mm.
LOWER CONTACT: C5210. T=0.10mm.
PEGS: BRASS.T=0.20mm

2.FINISH:

CONTACT: (SEE TABLE) GOLD PLATING ON CONTACT AREA.
GOLD FLASH MIN AU PLATING ON SOLDERTAILS
1.27um [50μ"] MIN. NICKEL UNDERPLATING OVER ALL
PEGS: 2.54μm [100μ"] MIN. BRIGHT-TIN OVER 1.27μm [50μ"] MIN. NICKEL PLATED.



RECOMMENDED PCB LAYOUT
(TOLERANCE=±0.05)

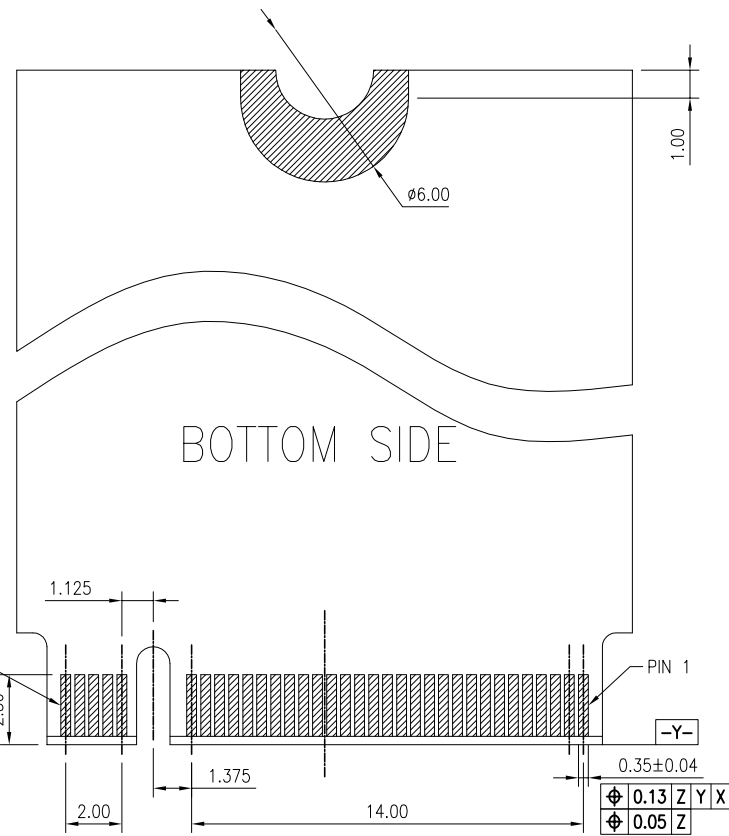
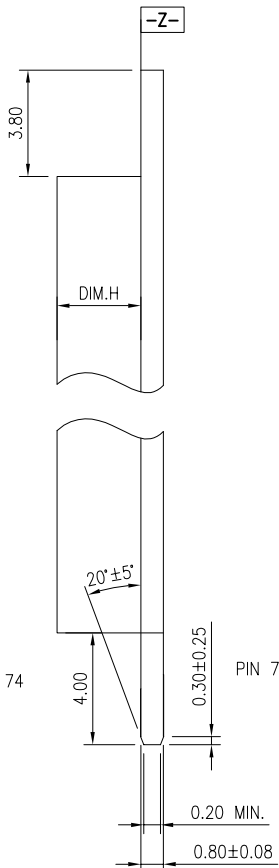
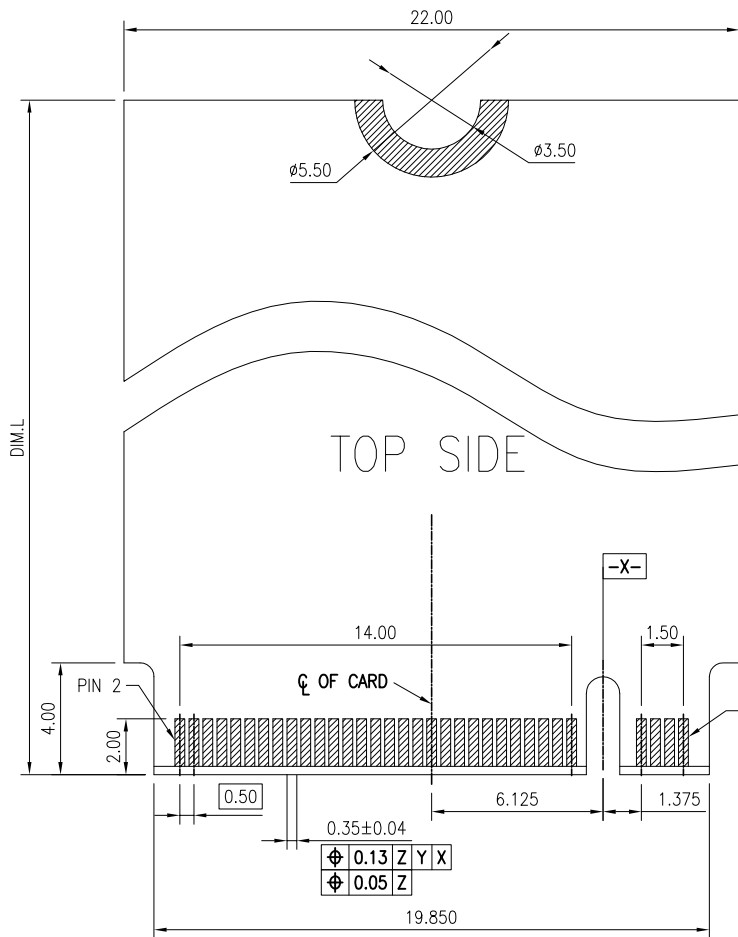
GP	10μ"	2NF23-0001-02
GP	G/F	2NF23-0001-01
environmental standards	MIN. GOLD THICKNESS	PART NUMBER

ECN(DCN) NO.	REV.	DATE	DESCRIPTION	CHANGE	APVD
	A1	12MAY15	ADD GP	CHU	D.Z
	A	20DEC12	PRELIMINARY	Y.J	D.Z

TOLERANCES UNLESS OTHERWISE SPECIFIED
.X ±0.30 X.* ±2"
.XX ±0.25 X.X* ±1"
XXX ±0.10

Singatron Enterprise Co., Ltd.				
TITLE	0.50Pitch 67Pin OF NGFF MINI PCI CONNECTOR (key M)			
DWN	CHUXINWEI	PART NO.	SEE TABLE	
CHKD	CYONG_JIANG	SCALE	1:1	UNIT: mm
APVD	DAVID_ZHONG	SIZE	A3	SHEET: 1 of 2
REV: A1				
CUSTOMER COPY				

1 2 3 4 5 6 7 8



1.50	30	TYPE 2
1.13	80	TYPE 1
DIM.H	DIM.L	TYPE

	A1	12MAY15	ADD GP	CHU	D.Z
	A	20DEC12	PRELIMINARY	Y.J	D.Z
ECN(DCN) NO.	REV.	DATE	DESCRIPTION	CHANGE	APVD

TOLERANCES UNLESS OTHERWISE SPECIFIED	
. ±0.30	X.* ±2'
.XX ±0.25	X.X* ±1'
.XXX ±0.15	
XXX ±0.10	

Singatron Enterprise Co., Ltd.				
TITLE	0.50Pitch 67Pin OF NGFF MINI PCI CONNECTOR (key M)			
DWN	CHUXINWEI	PART NO. SEE TABLE		
CHKD	CYONG_JIANG	SCALE 1:1	UNIT: mm	④ ↗
APVD	DAVID_ZHONG	SIZE: A3	SHEET: 2 of 2	REV: A1
CUSTOMER COPY				